

February 2001 Revised August 2001

74LCX162374

Low Voltage 16-Bit D-Type Flip-Flop with 5V Tolerant Inputs and Outputs and 26 Ω Series Resistors

General Description

The LCX162374 contains sixteen non-inverting D-type flip-flops with 3-STATE outputs and is intended for bus oriented applications. The device is byte controlled. A buffered clock (CP) and Output Enable $(\overline{\text{OE}})$ are common to each byte and can be shorted together for full 16-bit operation.

The LCX162374 is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment. The 26Ω series resistor in the output helps reduce output overshoot and undershoot.

The LCX162374 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- \blacksquare 2.3V–3.6V $\rm V_{CC}$ specifications provided
- \blacksquare Equivalent 26 Ω series resistor on outputs
- \blacksquare 7.0 ns t_{PD} max (V_{CC} = 3.3V), 20 μ A I_{CC} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- ± 12 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V

Machine model > 200V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA) (Preliminary)

Note 1: To ensure the high-impedance state during power up or down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

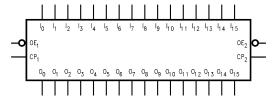
Ordering Code:

Order Number	Package Number	Package Description
74LCX162374GX (Note 2)	BGA54A (Preliminary)	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide [TAPE and REEL]
74LCX162374MEA (Note 3)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LCX162374MTD (Note 3)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 2: BGA package available in Tape and Reel only.

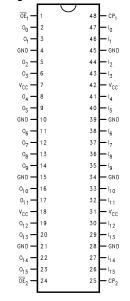
Note 3: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code

Logic Symbol

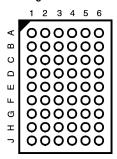


Connection Diagrams

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

Pin Names	Description
OE n	Output Enable Input (Active LOW)
CP _n	Clock Pulse Input
I ₀ -I ₁₅	Inputs
O ₀ -O ₁₅	Outputs
NC	No Connect

FBGA Pin Assignments

	1	2	3	4	5	6
Α	O ₀	NC	OE ₁	CP ₁	NC	I ₀
В	02	O ₁	NC	NC	I ₁	I ₂
С	O ₄	O ₃	V _{CC}	V _{CC}	I ₃	I ₄
D	O ₆	O ₅	GND	GND	I ₅	I ₆
E	Ο ₈	O ₇	GND	GND	I ₇	I ₈
F	O ₁₀	O ₉	GND	GND	l ₉	I ₁₀
G	O ₁₂	O ₁₁	V _{CC}	V _{CC}	I ₁₁	I ₁₂
Н	O ₁₄	O ₁₃	NC	NC	I ₁₃	I ₁₄
J	O ₁₅	NC	OE ₂	CP ₂	NC	I ₁₅

Truth Tables

	Inputs		Outputs
CP ₁	OE ₁	I ₀ –I ₇	O ₀ -O ₇
~	L	Н	Н
~	L	L	L
L	L	Χ	O ₀
Х	Н	X	Z

	Inputs		Outputs
CP ₂	OE ₂	I ₈ –I ₁₅	O ₈ -O ₁₅
~	L	Н	Н
~	L	L	L
L	L	Χ	O_0
Х	Н	X	Z

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial Z = High Impedance

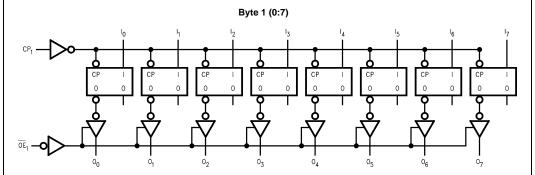
O₀ = Previous O₀ before HIGH-to-LOW of CP

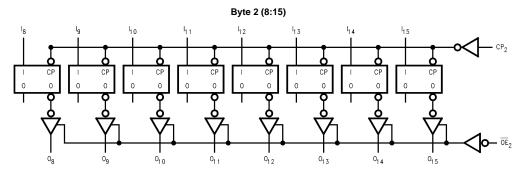
Functional Description

The LCX162374 consists of sixteen edge-triggered flip-flops with individual D-type inputs and 3-STATE true outputs. The device is byte controlled with each byte functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation. Each byte has a buffered clock and buffered Output Enable common to all flip-flops within that byte. The description which follows applies to each byte. Each flip-flop will store

the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CPn) transition. With the Output Enable (\overline{OE}_n) LOW, the contents of the flip-flops are available at the outputs. When \overline{OE}_n is HIGH, the outputs go to the high impedance state. Operation of the \overline{OE}_n input does not affect the state of the flip-flops

Logic Diagrams





Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings(Note 4)

Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	-0.5 to +7.0		V
Vo	DC Output Voltage	-0.5 to +7.0	3-STATE	V
		-0.5 to $V_{CC} + 0.5$	Output in HIGH or LOW State (Note 5)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	$V_O > V_{CC}$	IIIA
I _O	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current per Supply Pin	±100		mA
I _{GND}	DC Ground Current per Ground Pin	±100		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions (Note 6)

Symbol	Parameter		Min	Max	Units
V _{CC}	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	V
V _I	Input Voltage		0	5.5	V
Vo	Output Voltage	HIGH or LOW State	0	V _{CC}	V
		3-STATE	0	5.5	V
I _{OH} /I _{OL}	Output Current	$V_{CC} = 3.0V - 3.6V$		±12	
		$V_{CC} = 2.7V - 3.0V$ $V_{CC} = 2.3V - 2.7V$		±8	mA
		$V_{CC} = 2.3V - 2.7V$		±4	
T _A	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$		0	10	ns/V

Note 4: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 5: I_O Absolute Maximum Rating must be observed.

Note 6: Floating or unused control inputs must be HIGH or LOW.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V_{CC} $T_A = -40^{\circ}C$	$T_A = -40^{\circ}C$ to $+85^{\circ}C$		Units
Зуппоп	Farameter	Conditions	(V)	Min	Max	Ullits
V _{IH}	HIGH Level Input Voltage		2.3 – 2.7	1.7		V
			2.7 – 3.6	2.0		v
V _{IL}	LOW Level Input Voltage		2.3 – 2.7		0.7	V
			2.7 – 3.6		8.0	v
V _{OH}	HIGH Level Output Voltage	I _{OH} = -100 μA	2.3 – 3.6	V _{CC} - 0.2		
		$I_{OH} = -4 \text{ mA}$	2.3	1.8		
		$I_{OH} = -4 \text{ mA}$	2.7	2.2		V
		$I_{OH} = -6 \text{ mA}$	3.0	2.4		v
		$I_{OH} = -8 \text{ mA}$	2.7	2.0		
		I _{OH} = -12 mA	3.0	2.0		
V _{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	2.3 – 3.6		0.2	
		I _{OL} = 4 mA	2.3		0.6	
		I _{OL} = 4 mA	2.7		0.4	V
		I _{OL} = 6 mA	3.0		0.55	l v
		I _{OL} = 8 mA	2.7		0.6	
		I _{OL} = 12 mA	3.0		0.8	
I _I	Input Leakage Current	$0 \le V_I \le 5.5V$	2.3 – 3.6		±5.0	μΑ
I _{OZ}	3-STATE Output Leakage	0 ≤ V _O ≤ 5.5V	2.3 – 3.6		±5.0	
		$V_I = V_{IH}$ or V_{IL}	2.3 – 3.6		±3.0	μΑ

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC}	T _A = -40°	C to +85°C	Units
Cymbol	i arameter	Conditions	(V)	Min	Max	Oiiits
I _{OFF}	Power-Off Leakage Current	V_I or $V_O = 5.5V$	0		10	μΑ
I _{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND	2.3 – 3.6		20	μА
		3.6V ≤ V _I , V _O ≤ 5.5V (Note 7)	2.3 – 3.6		±20	μΛ
ΔI_{CC}	Increase in I _{CC} per Input	$V_{IH} = V_{CC} - 0.6V$	2.3 - 3.6		500	μΑ

Note 7: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

			$T_A = -40^\circ$ to $+85^\circ$ C, $R_L = 500\Omega$					
0	Parameter	V _{CC} = 3.	$V_{CC} = 3.3V \pm 0.3V$		= 2.7V V _{CC} = 2		5V ± 0.2V	
Symbol	Farameter	C _L =	50 pF	C _L =	50 pF	C _L =	30 pF	Units
		Min	Max	Min	Max	Min	Max	
f _{MAX}	Maximum Clock Frequency	170						MHz
t _{PHL}	Propagation Delay	1.5	7.0	1.5	7.3	1.5	8.4	
t _{PLH}	CP to O _n	1.5	7.0	1.5	7.3	1.5	8.4	ns
t _{PZL}	Output Enable time	1.5	6.9	1.5	7.1	1.5	9.0	ns
t_{PZH}		1.5	6.9	1.5	7.1	1.5	9.0	115
t _{PLZ}	Output Disable Time	1.5	6.0	1.5	6.2	1.5	7.2	
t_{PHZ}		1.5	6.0	1.5	6.2	1.5	7.2	ns
t _S	Setup Time	2.5		2.5		3.0		ns
t _H	Hold Time	1.5		1.5		2.0		ns
t _W	Pulse Width	3.0		3.0		3.5		ns
toshl	Output to Output Skew (Note 8)		1.0					ns
t _{OSLH}			1.0					115

Note 8: Skew is defined as the absolute value of the differences between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}). Parameter guaranteed by design.

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V _{CC}	T _A = 25°C	Units
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V	3.3	0.35	V
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	0.25	v
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.35	V
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	-0.25	v

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = Open, V_I = 0V \text{ or } V_{CC}$	7	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V$, $V_{I} = 0V$ or V_{CC} , $f = 10$ MHz	20	pF

AC LOADING and WAVEFORMS Generic for LCX Family

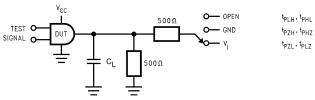
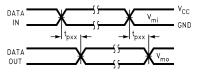
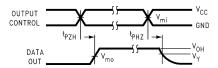


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

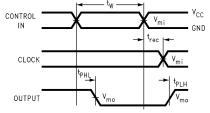
Test	Switch		
t _{PLH} , t _{PHL}	Open		
t _{PZL} , t _{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3$ V, and 2.7V V_{CC} x 2 at $V_{CC} = 2.5 \pm 0.2$ V		
t _{PZH} , t _{PHZ}	GND		



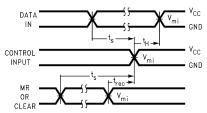
Waveform for Inverting and Non-Inverting Functions



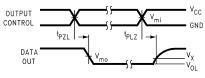
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

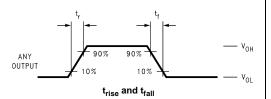
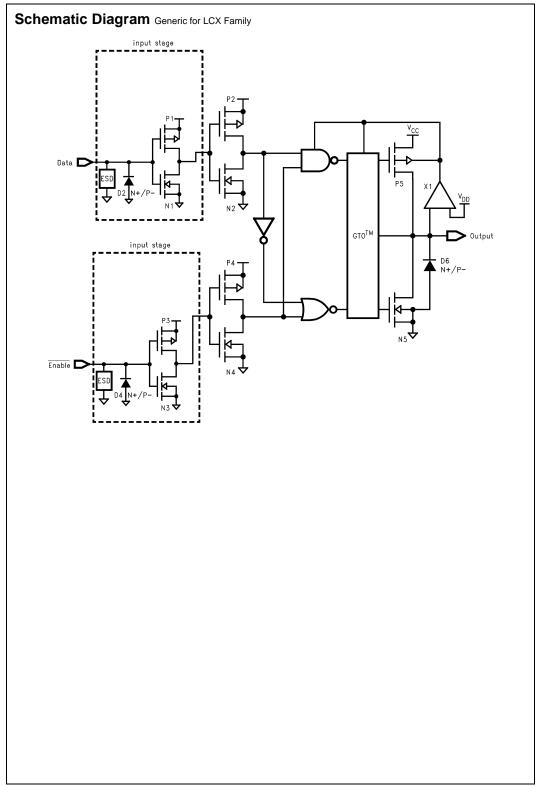
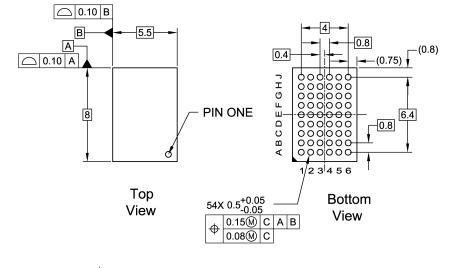


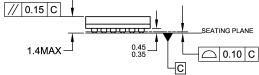
FIGURE 2. Waveforms (Input Characteristics; f =1MHz, $t_r = t_f = 3ns$)

Symbol	V _{cc}			
	$3.3V \pm 0.3V$	2.7V	$\textbf{2.5V} \pm \textbf{0.2V}$	
V_{mi}	1.5V	1.5V	V _{CC} /2	
V _{mo}	1.5V	1.5V	V _{CC} /2	
V _x	V _{OL} + 0.3V	V _{OL} + 0.3V	V _{OL} + 0.15V	
V _v	V _{OH} – 0.3V	V _{OH} – 0.3V	V _{OH} – 0.15V	



Physical Dimensions inches (millimeters) unless otherwise noted



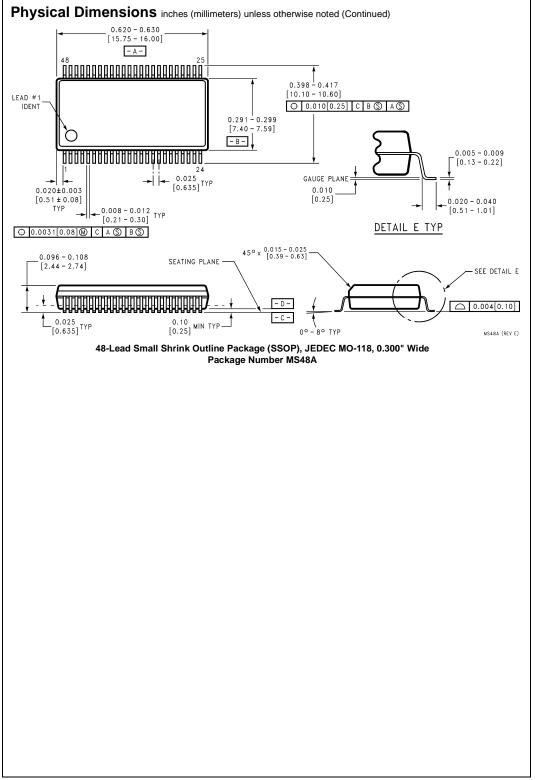


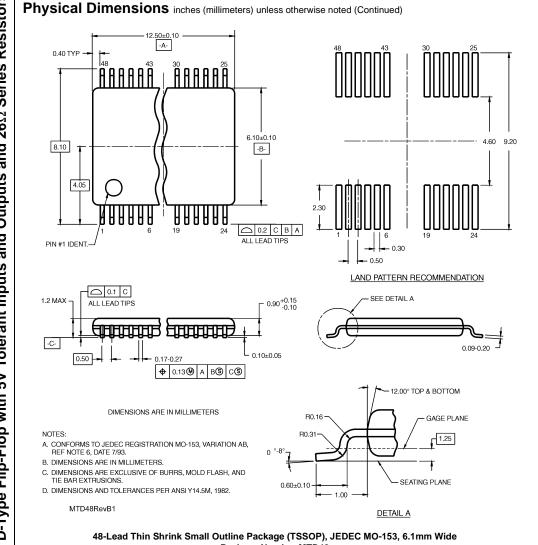
NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- **B. ALL DIMENSIONS IN MILLIMETERS**
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
 .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
 D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A Preliminary





Package Number MTD48

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